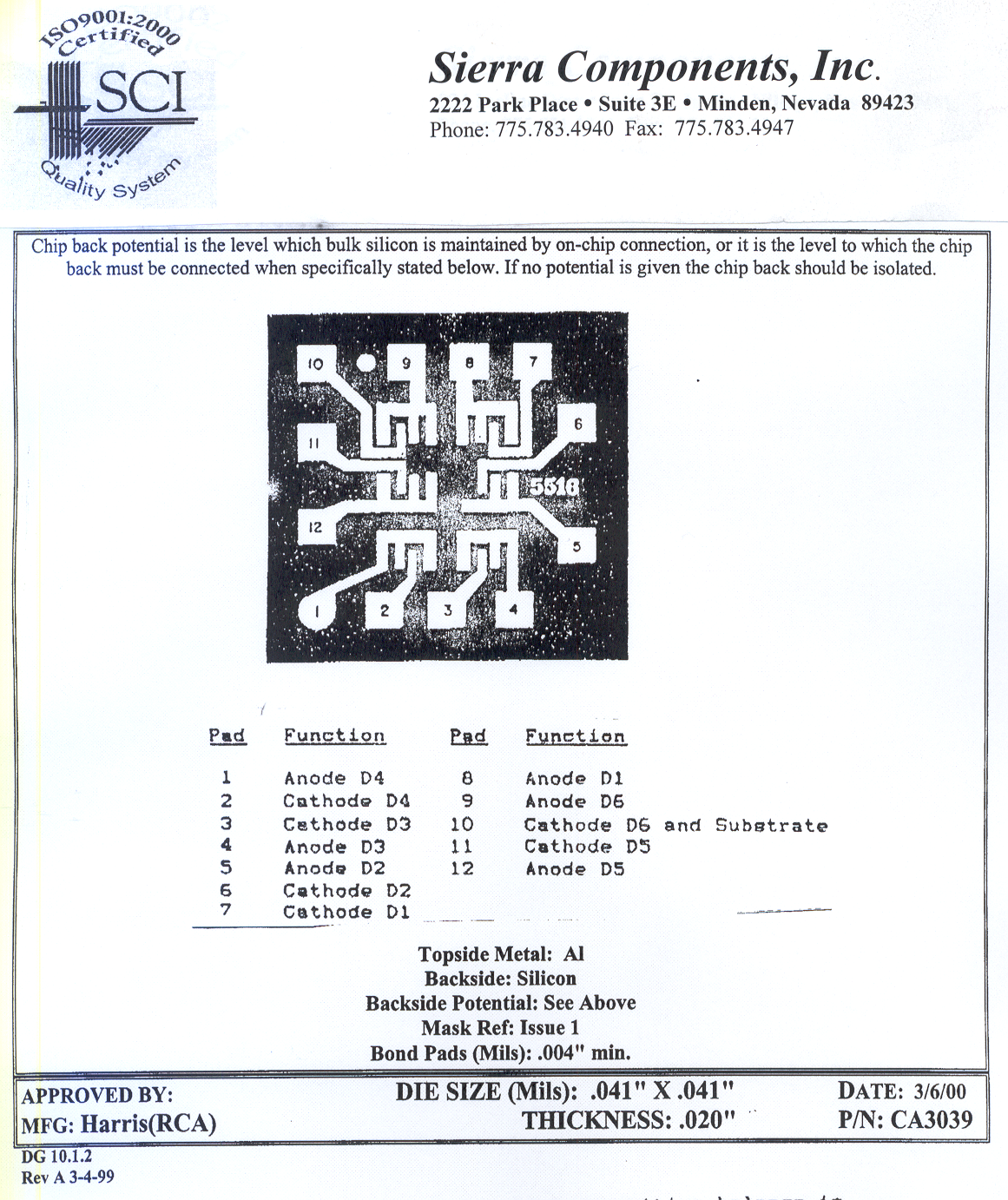
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION**

1. **D4 Anode**
2. **D4 Cathode**
3. **D3 Cathode**
4. **D3 Cathode**
5. **D2 Anode**
6. **D2 Cathode**
7. **D1 Cathode**
8. **D1 Anode**
9. **D5 Anode**
10. **D6 & Substrate Cathode**
11. **D5 Cathode**
12. **D5 Anode**

****

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: See above**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .041” X .041” DATE: 2/12/16**

**MFG: HARRIS / RCA THICKNESS .020” P/N: CA3039**

**DG 10.1.2**

#### Rev B, 7/19/02